CMOS VLSI Design
A Circuits and Systems Perspective
Fourth Edition
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To Avril, Melissa, Tamara, Nicky, Jocelyn, Makayla, Emily, Danika, Dan and Simon
N. W.

To Jennifer, Samuel, and Abraham
D. M. H.
Preface xxv

Chapter 1 Introduction

1.1 A Brief History .......................................................... 1
1.2 Preview ................................................................. 6
1.3 MOS Transistors .......................................................... 6
1.4 CMOS Logic .............................................................. 9
   1.4.1 The Inverter 9
   1.4.2 The NAND Gate 9
   1.4.3 CMOS Logic Gates 9
   1.4.4 The NOR Gate 11
   1.4.5 Compound Gates 11
   1.4.6 Pass Transistors and Transmission Gates 12
   1.4.7 Tristates 14
   1.4.8 Multiplexers 15
   1.4.9 Sequential Circuits 16
1.5 CMOS Fabrication and Layout ....................................... 19
   1.5.1 Inverter Cross-Section 19
   1.5.2 Fabrication Process 20
   1.5.3 Layout Design Rules 24
   1.5.4 Gate Layouts 27
   1.5.5 Stick Diagrams 28
1.6 Design Partitioning ..................................................... 29
   1.6.1 Design Abstractions 30
   1.6.2 Structured Design 31
   1.6.3 Behavioral, Structural, and Physical Domains 31
1.7 Example: A Simple MIPS Microprocessor ............................ 33
   1.7.1 MIPS Architecture 33
   1.7.2 Multicycle MIPS Microarchitectures 34
1.8 Logic Design ............................................................ 38
   1.8.1 Top-Level Interfaces 38
   1.8.2 Block Diagrams 38
   1.8.3 Hierarchy 40
   1.8.4 Hardware Description Languages 40
1.9 Circuit Design .......................................................... 42
Chapter 2 MOS Transistor Theory

2.1 Introduction ...................................................... 61
2.2 Long-Channel I-V Characteristics ................................ 64
2.3 C-V Characteristics ................................................ 68
  2.3.1 Simple MOS Capacitance Models 68
  2.3.2 Detailed MOS Gate Capacitance Model 70
  2.3.3 Detailed MOS Diffusion Capacitance Model 72
2.4 Nonideal I-V Effects ............................................... 74
  2.4.1 Mobility Degradation and Velocity Saturation 75
  2.4.2 Channel Length Modulation 78
  2.4.3 Threshold Voltage Effects 79
  2.4.4 Leakage 80
  2.4.5 Temperature Dependence 85
  2.4.6 Geometry Dependence 86
  2.4.7 Summary 86
2.5 DC Transfer Characteristics ...................................... 87
  2.5.1 Static CMOS Inverter DC Characteristics 88
  2.5.2 Beta Ratio Effects 90
  2.5.3 Noise Margin 91
  2.5.4 Pass Transistor DC Characteristics 92
2.6 Pitfalls and Fallacies ............................................. 93
Summary 94
Exercises 95

Chapter 3 CMOS Processing Technology

3.1 Introduction ..................................................... 99
3.2 CMOS Technologies .............................................. 100
  3.2.1 Wafer Formation 100
  3.2.2 Photolithography 101
3.2.3 Well and Channel Formation 103
3.2.4 Silicon Dioxide (SiO2) 105
3.2.5 Isolation 106
3.2.6 Gate Oxide 107
3.2.7 Gate and Source/Drain Formations 108
3.2.8 Contacts and Metallization 110
3.2.9 Passivation 112
3.2.10 Metrology 112

3.3 Layout Design Rules .................................................. 113
3.3.1 Design Rule Background 113
3.3.2 Scribe Line and Other Structures 116
3.3.3 MOSIS Scalable CMOS Design Rules 117
3.3.4 Micron Design Rules 118

3.4 CMOS Process Enhancements ........................................ 119
3.4.1 Transistors 119
3.4.2 Interconnect 122
3.4.3 Circuit Elements 124
3.4.4 Beyond Conventional CMOS 129

3.5 Technology-Related CAD Issues ................................... 130
3.5.1 Design Rule Checking (DRC) 131
3.5.2 Circuit Extraction 132

3.6 Manufacturing Issues ............................................... 133
3.6.1 Antenna Rules 133
3.6.2 Layer Density Rules 134
3.6.3 Resolution Enhancement Rules 134
3.6.4 Metal Slotting Rules 135
3.6.5 Yield Enhancement Guidelines 135

3.7 Pitfalls and Fallacies .................................................. 136
3.8 Historical Perspective ............................................... 137

Summary 139
Exercises 139

Chapter 4 Delay

4.1 Introduction ............................................................. 141
4.1.1 Definitions 141
4.1.2 Timing Optimization 142

4.2 Transient Response ................................................... 143

4.3 RC Delay Model ....................................................... 146
4.3.1 Effective Resistance 146
4.3.2 Gate and Diffusion Capacitance 147
4.3.3 Equivalent RC Circuits 147
4.3.4 Transient Response 148
4.3.5 Elmore Delay 150
4.3.6 Layout Dependence of Capacitance 153
4.3.7 Determining Effective Resistance 154

4.4 Linear Delay Model ................................................. 155
4.4.1 Logical Effort 156
4.4.2 Parasitic Delay 156
4.4.3 Delay in a Logic Gate 158
4.4.4 Drive 159
4.4.5 Extracting Logical Effort from Datasheets 159
4.4.6 Limitations to the Linear Delay Model 160

4.5 Logical Effort of Paths ................................................. 163
4.5.1 Delay in Multistage Logic Networks 163
4.5.2 Choosing the Best Number of Stages 166
4.5.3 Example 168
4.5.4 Summary and Observations 169
4.5.5 Limitations of Logical Effort 171
4.5.6 Iterative Solutions for Sizing 171

4.6 Timing Analysis Delay Models ........................................ 173
4.6.1 Slope-Based Linear Model 173
4.6.2 Nonlinear Delay Model 174
4.6.3 Current Source Model 174

4.7 Pitfalls and Fallacies ................................................. 174

4.8 Historical Perspective ................................................. 175

Summary 176
Exercises 176

Chapter 5 Power

5.1 Introduction ......................................................... 181
5.1.1 Definitions 182
5.1.2 Examples 182
5.1.3 Sources of Power Dissipation 184

5.2 Dynamic Power ...................................................... 185
5.2.1 Activity Factor 186
5.2.2 Capacitance 188
5.2.3 Voltage 190
5.2.4 Frequency 192
5.2.5 Short-Circuit Current 193
5.2.6 Resonant Circuits 193

5.3 Static Power .................................................... 194
5.3.1 Static Power Sources 194
5.3.2 Power Gating 197
5.3.3 Multiple Threshold Voltages and Oxide Thicknesses 199
## Chapter 7 Robustness

### 7.1 Introduction ........................................... 241

### 7.2 Variability ............................................. 241
   7.2.1 Supply Voltage 242
   7.2.2 Temperature 242
   7.2.3 Process Variation 243
   7.2.4 Design Corners 244

### 7.3 Reliability ............................................. 246
   7.3.1 Reliability Terminology 246
   7.3.2 Oxide Wearout 247
   7.3.3 Interconnect Wearout 249
   7.3.4 Soft Errors 251
   7.3.5 Overvoltage Failure 252
   7.3.6 Latchup 253

### 7.4 Scaling ................................................. 254
   7.4.1 Transistor Scaling 255
   7.4.2 Interconnect Scaling 257
   7.4.3 International Technology Roadmap for Semiconductors 258
   7.4.4 Impacts on Design 259

### 7.5 Statistical Analysis of Variability ...................... 263
   7.5.1 Properties of Random Variables 263
   7.5.2 Variation Sources 266
   7.5.3 Variation Impacts 269

### 7.6 Variation-Tolerant Design .............................. 274
   7.6.1 Adaptive Control 275
   7.6.2 Fault Tolerance 275

### 7.7 Pitfalls and Fallacies .................................... 277

### 7.8 Historical Perspective ................................... 278

**Summary** 284
**Exercises** 284

## Chapter 8 Circuit Simulation

### 8.1 Introduction ........................................... 287

### 8.2 A SPICE Tutorial ....................................... 288
   8.2.1 Sources and Passive Components 288
   8.2.2 Transistor DC Analysis 292
   8.2.3 Inverter Transient Analysis 292
   8.2.4 Subcircuits and Measurement 294
   8.2.5 Optimization 296
   8.2.6 Other HSPICE Commands 298
8.3 Device Models ............................................................... 298
  8.3.1 Level 1 Models 299
  8.3.2 Level 2 and 3 Models 300
  8.3.3 BSIM Models 300
  8.3.4 Diffusion Capacitance Models 300
  8.3.5 Design Corners 302
8.4 Device Characterization .................................................. 303
  8.4.1 I-V Characteristics 303
  8.4.2 Threshold Voltage 306
  8.4.3 Gate Capacitance 308
  8.4.4 Parasitic Capacitance 308
  8.4.5 Effective Resistance 310
  8.4.6 Comparison of Processes 311
  8.4.7 Process and Environmental Sensitivity 313
8.5 Circuit Characterization .................................................... 313
  8.5.1 Path Simulations 313
  8.5.2 DC Transfer Characteristics 315
  8.5.3 Logical Effort 315
  8.5.4 Power and Energy 318
  8.5.5 Simulating Mismatches 319
  8.5.6 Monte Carlo Simulation 319
8.6 Interconnect Simulation ..................................................... 319
8.7 Pitfalls and Fallacies ......................................................... 322
  Summary 324
  Exercises 324

Chapter 9  Combinational Circuit Design

9.1 Introduction ................................................................. 327
9.2 Circuit Families ........................................................... 328
  9.2.1 Static CMOS 329
  9.2.2 Ratioed Circuits 334
  9.2.3 Cascode Voltage Switch Logic 339
  9.2.4 Dynamic Circuits 339
  9.2.5 Pass-Transistor Circuits 349
9.3 Circuit Pitfalls .............................................................. 354
  9.3.1 Threshold Drops 355
  9.3.2 Ratio Failures 355
  9.3.3 Leakage 356
  9.3.4 Charge Sharing 356
  9.3.5 Power Supply Noise 356
  9.3.6 Hot Spots 357
9.3.7 Minority Carrier Injection 357
9.3.8 Back-Gate Coupling 358
9.3.9 Diffusion Input Noise Sensitivity 358
9.3.10 Process Sensitivity 358
9.3.11 Example: Domino Noise Budgets 359

9.4 More Circuit Families ................................. 360
9.5 Silicon-On-Insulator Circuit Design ..................... 360
  9.5.1 Floating Body Voltage 361
  9.5.2 SOI Advantages 362
  9.5.3 SOI Disadvantages 362
  9.5.4 Implications for Circuit Styles 363
  9.5.5 Summary 364

9.6 Subthreshold Circuit Design ............................. 364
  9.6.1 Sizing 365
  9.6.2 Gate Selection 365

9.7 Pitfalls and Fallacies ............................... 366
9.8 Historical Perspective ................................. 367
Summary 369
Exercises 370

Chapter 10 Sequential Circuit Design

10.1 Introduction ........................................... 375
10.2 Sequencing Static Circuits ............................. 376
  10.2.1 Sequencing Methods 376
  10.2.2 Max-Delay Constraints 379
  10.2.3 Min-Delay Constraints 383
  10.2.4 Time Borrowing 386
  10.2.5 Clock Skew 389

10.3 Circuit Design of Latches and Flip-Flops ............. 391
  10.3.1 Conventional CMOS Latches 392
  10.3.2 Conventional CMOS Flip-Flops 393
  10.3.3 Pulsed Latches 395
  10.3.4 Retestable Latches and Flip-Flops 396
  10.3.5 Enabled Latches and Flip-Flops 397
  10.3.6 Incorporating Logic into Latches 398
  10.3.7 Klass Semidynamic Flip-Flop (SDFF) 399
  10.3.8 Differential Flip-Flops 399
  10.3.9 Dual Edge-Triggered Flip-Flops 400
  10.3.10 Radiation-Hardened Flip-Flops 401
  10.3.11 True Single-Phase-Clock (TSPC) Latches and Flip-Flops 402

10.4 Static Sequencing Element Methodology ............... 402
  10.4.1 Choice of Elements 403
  10.4.2 Characterizing Sequencing Element Delays 405
10.4.3 State Retention Registers 408
10.4.4 Level-Converter Flip-Flops 408
10.4.5 Design Margin and Adaptive Sequential Elements 409
10.4.6 Two-Phase Timing Types 411
10.5 Sequencing Dynamic Circuits ........................................ 411
10.6 Synchronizers ............................................................... 411
10.6.1 Metastability 412
10.6.2 A Simple Synchronizer 415
10.6.3 Communicating Between Asynchronous Clock Domains 416
10.6.4 Common Synchronizer Mistakes 417
10.6.5 Arbiters 419
10.6.6 Degrees of Synchrony 419
10.7 Wave Pipelining ............................................................ 420
10.8 Pitfalls and Fallacies ....................................................... 422
10.9 Case Study: Pentium 4 and Itanium 2 Sequencing Methodologies .. 423
Summary 423
Exercises 425

Chapter 11 Datapath Subsystems

11.1 Introduction ................................................................. 429
11.2 Addition/Subtraction ..................................................... 429
11.2.1 Single-Bit Addition 430
11.2.2 Carry-Propagate Addition 434
11.2.3 Subtraction 458
11.2.4 Multiple-Input Addition 458
11.2.5 Flagged Prefix Adders 459
11.3 One/Zero Detectors ....................................................... 461
11.4 Comparators ............................................................... 462
11.4.1 Magnitude Comparator 462
11.4.2 Equality Comparator 462
11.4.3 \( K = A + B \) Comparator 463
11.5 Counters ................................................................. 463
11.5.1 Binary Counters 464
11.5.2 Fast Binary Counters 465
11.5.3 Ring and Johnson Counters 466
11.5.4 Linear-Feedback Shift Registers 466
11.6 Boolean Logical Operations ........................................... 468
11.7 Coding ................................................................. 468
11.7.1 Parity 468
11.7.2 Error-Correcting Codes 468
11.7.3 Gray Codes 470
11.7.4 XOR/XNOR Circuit Forms 471
11.8 Shifters ................................................................. 472
   11.8.1 Funnel Shifter 473
   11.8.2 Barrel Shifter 475
   11.8.3 Alternative Shift Functions 476
11.9 Multiplication .......................................................... 476
   11.9.1 Unsigned Array Multiplication 478
   11.9.2 Two’s Complement Array Multiplication 479
   11.9.3 Booth Encoding 480
   11.9.4 Column Addition 485
   11.9.5 Final Addition 489
   11.9.6 Fused Multiply-Add 490
   11.9.7 Serial Multiplication 490
   11.9.8 Summary 490
11.10 Parallel-Prefix Computations ........................................ 491
11.11 Pitfalls and Fallacies .............................................. 493
Summary 494
Exercises 494

Chapter 12 **Array Subsystems**

12.1 Introduction ....................................................... 497
12.2 SRAM ................................................................. 498
   12.2.1 SRAM Cells 499
   12.2.2 Row Circuity 506
   12.2.3 Column Circuity 510
   12.2.4 Multi-Ported SRAM and Register Files 514
   12.2.5 Large SRAMS 515
   12.2.6 Low-Power SRAMS 517
   12.2.7 Area, Delay, and Power of RAMs and Register Files 520
12.3 DRAM ................................................................. 522
   12.3.1 Subarray Architectures 523
   12.3.2 Column Circuity 525
   12.3.3 Embedded DRAM 526
12.4 Read-Only Memory .................................................. 527
   12.4.1 Programmable ROMs 529
   12.4.2 NAND ROMs 530
   12.4.3 Flash 531
12.5 Serial Access Memories ............................................. 533
   12.5.1 Shift Registers 533
   12.5.2 Queues (FIFO, LIFO) 533
12.6 Content-Addressable Memory ...................................... 535
12.7 Programmable Logic Arrays ........................................ 537
12.8 Robust Memory Design .................................................. 541
  12.8.1 Redundancy  541
  12.8.2 Error Correcting Codes (ECC)  543
  12.8.3 Radiation Hardening  543
12.9 Historical Perspective .................................................. 544
Summary  545
Exercises  546

Chapter 13 Special-Purpose Subsystems

13.1 Introduction .............................................................. 549
13.2 Packaging and Cooling .................................................... 549
  13.2.1 Package Options  549
  13.2.2 Chip-to-Package Connections  551
  13.2.3 Package Parasitics  552
  13.2.4 Heat Dissipation  552
  13.2.5 Temperature Sensors  553
13.3 Power Distribution ....................................................... 555
  13.3.1 On-Chip Power Distribution Network  556
  13.3.2 IR Drops  557
  13.3.3 L di/dt Noise  558
  13.3.4 On-Chip Bypass Capacitance  559
  13.3.5 Power Network Modeling  560
  13.3.6 Power Supply Filtering  564
  13.3.7 Charge Pumps  564
  13.3.8 Substrate Noise  565
  13.3.9 Energy Scavenging  565
13.4 Clocks .............................................................. 566
  13.4.1 Definitions  566
  13.4.2 Clock System Architecture  568
  13.4.3 Global Clock Generation  569
  13.4.4 Global Clock Distribution  571
  13.4.5 Local Clock Gaters  575
  13.4.6 Clock Skew Budgets  577
  13.4.7 Adaptive Deskewing  579
13.5 PLLs and DLLs ......................................................... 580
  13.5.1 PLLs  580
  13.5.2 DLLs  587
  13.5.3 Pitfalls  589
13.6 I/O .............................................................. 590
  13.6.1 Basic I/O Pad Circuits  591
  13.6.2 Electrostatic Discharge Protection  593
  13.6.3 Example: MOSIS I/O Pads  594
  13.6.4 Mixed-Voltage I/O  596
13.7 High-Speed Links ......................................................... 597
  13.7.1 High-Speed I/O Channels  597
  13.7.2 Channel Noise and Interference  600
  13.7.3 High-Speed Transmitters and Receivers  601
  13.7.4 Synchronous Data Transmission  606
  13.7.5 Clock Recovery in Source-Synchronous Systems  606
  13.7.6 Clock Recovery in Mesochronous Systems  608
  13.7.7 Clock Recovery in Pleisochronous Systems  610
13.8 Random Circuits ......................................................... 610
  13.8.1 True Random Number Generators  610
  13.8.2 Chip Identification  611
13.9 Pitfalls and Fallacies ..................................................... 612
Summary  613
Exercises  614

Chapter 14 Design Methodology and Tools

14.1 Introduction .............................................................. 615
14.2 Structured Design Strategies ........................................... 617
  14.2.1 A Software Radio—A System Example  618
  14.2.2 Hierarchy  620
  14.2.3 Regularity  623
  14.2.4 Modularity  625
  14.2.5 Locality  626
  14.2.6 Summary  627
14.3 Design Methods .......................................................... 627
  14.3.1 Microprocessor/DSP  627
  14.3.2 Programmable Logic  628
  14.3.3 Gate Array and Sea of Gates Design  631
  14.3.4 Cell-Based Design  632
  14.3.5 Full Custom Design  634
  14.3.6 Platform-Based Design—System on a Chip  635
  14.3.7 Summary  636
14.4 Design Flows ............................................................. 636
  14.4.1 Behavioral Synthesis Design Flow (ASIC Design Flow)  637
  14.4.2 Automated Layout Generation  641
  14.4.3 Mixed-Signal or Custom-Design Flow  645
14.5 Design Economics ........................................................ 646
  14.5.1 Non-Recurring Engineering Costs (NREs)  647
  14.5.2 Recurring Costs  649
  14.5.3 Fixed Costs  650
  14.5.4 Schedule  651
  14.5.5 Personpower  653
  14.5.6 Project Management  653
  14.5.7 Design Reuse  654
14.6 Data Sheets and Documentation .................................................. 655
  14.6.1 The Summary 655
  14.6.2 Pinout 655
  14.6.3 Description of Operation 655
  14.6.4 DC Specifications 655
  14.6.5 AC Specifications 656
  14.6.6 Package Diagram 656
  14.6.7 Principles of Operation Manual 656
  14.6.8 User Manual 656

14.7 CMOS Physical Design Styles .................................................... 656

14.8 Pitfalls and Fallacies ............................................................... 657

Exercises 657

Chapter 15 Testing, Debugging, and Verification

15.1 Introduction ................................................................. 659
  15.1.1 Logic Verification 660
  15.1.2 Debugging 662
  15.1.3 Manufacturing Tests 664

15.2 Testers, Test Fixtures, and Test Programs .................................. 666
  15.2.1 Testers and Test Fixtures 666
  15.2.2 Test Programs 668
  15.2.3 Handlers 669

15.3 Logic Verification Principles .................................................. 670
  15.3.1 Test Vectors 670
  15.3.2 Testbenches and Harnesses 671
  15.3.3 Regression Testing 671
  15.3.4 Version Control 672
  15.3.5 Bug Tracking 673

15.4 Silicon Debug Principles ...................................................... 673

15.5 Manufacturing Test Principles ................................................ 676
  15.5.1 Fault Models 677
  15.5.2 Observability 679
  15.5.3 Controllability 679
  15.5.4 Repeatability 679
  15.5.5 Survivability 679
  15.5.6 Fault Coverage 680
  15.5.7 Automatic Test Pattern Generation (ATPG) 680
  15.5.8 Delay Fault Testing 680

15.6 Design for Testability ............................................................ 681
  15.6.1 Ad Hoc Testing 681
  15.6.2 Scan Design 682
  15.6.3 Built-In Self-Test (BIST) 684
  15.6.4 IDDQ Testing 687
  15.6.5 Design for Manufacturability 687
15.7 Boundary Scan ............................................. 688
15.8 Testing in a University Environment ...................... 689
15.9 Pitfalls and Fallacies ........................................ 690
Summary 697
Exercises 697

Appendix A Hardware Description Languages

A.1 Introduction .................................................. 699
A.1.1 Modules 700
A.1.2 Simulation and Synthesis 701
A.2 Combinational Logic .......................................... 702
A.2.1 Bitwise Operators 702
A.2.2 Comments and White Space 703
A.2.3 Reduction Operators 703
A.2.4 Conditional Assignment 704
A.2.5 Internal Variables 706
A.2.6 Precedence and Other Operators 708
A.2.7 Numbers 708
A.2.8 Zs and Xs 709
A.2.9 Bit Swizzling 711
A.2.10 Delays 712
A.3 Structural Modeling ........................................... 713
A.4 Sequential Logic ............................................ 717
A.4.1 Registers 717
A.4.2 Resettable Registers 718
A.4.3 Enabled Registers 719
A.4.4 Multiple Registers 720
A.4.5 Latches 721
A.4.6 Counters 722
A.4.7 Shift Registers 724
A.5 Combinational Logic with Always / Process Statements .... 724
A.5.1 Case Statements 726
A.5.2 If Statements 729
A.5.3 SystemVerilog Casez 731
A.5.4 Blocking and Nonblocking Assignments 731
A.6 Finite State Machines ......................................... 735
A.6.1 FSM Example 735
A.6.2 State Enumeration 736
A.6.3 FSM with Inputs 738
A.7 Type Idiosyncracies .......................................... 740
A.8 Parameterized Modules ................................................. 742
A.9 Memory ................................................................. 745
  A.9.1 RAM 745
  A.9.2 Multiported Register Files 747
  A.9.3 ROM 748
A.10 Testbenches ........................................................... 749
A.11 SystemVerilog Netlists ............................................. 754
A.12 Example: MIPS Processor ......................................... 755
  A.12.1 Testbench 756
  A.12.2 SystemVerilog 757
  A.12.3 VHDL 766

Exercises 776

References 785

Index 817

Credits 838
Preface

In the two-and-a-half decades since the first edition of this book was published, CMOS technology has claimed the preeminent position in modern electrical system design. It has enabled the widespread use of wireless communication, the Internet, and personal computers. No other human invention has seen such rapid growth for such a sustained period. The transistor counts and clock frequencies of state-of-the-art chips have grown by orders of magnitude.

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This edition has been heavily revised to reflect the rapid changes in integrated circuit design over the past six years. While the basic principles are largely the same, power consumption and variability have become primary factors for chip design. The book has been reorganized to emphasize the key factors: delay, power, interconnect, and robustness. Other chapters have been reordered to reflect the order in which we teach the material.

How to Use This Book

This book intentionally covers more breadth and depth than any course would cover in a semester. It is accessible for a first undergraduate course in VLSI, yet detailed enough for advanced graduate courses and is useful as a reference to the practicing engineer. You are encouraged to pick and choose topics according to your interest. Chapter 1 previews the entire field, while subsequent chapters elaborate on specific topics. Sections are marked with the “Optional” icon (shown here in the margin) if they are not needed to understand subsequent sections. You may skip them on a first reading and return when they are relevant to you.

We have endeavored to include figures whenever possible (“a picture is worth a thousand words”) to trigger your thinking. As you encounter examples throughout the text, we urge you to think about them before reading the solutions. We have also provided extensive references for those who need to delve deeper into topics introduced in this text. We
have emphasized the best practices that are used in industry and warned of pitfalls and fallacies. Our judgments about the merits of circuits may become incorrect as technology and applications change, but we believe it is the responsibility of a writer to attempt to call out the most relevant information.

**Supplements**

Numerous supplements are available on the Companion Web site for the book, www_cmosvlsi.com. Supplements to help students with the course include:

* A lab manual with laboratory exercises involving the design of an 8-bit microprocessor covered in Chapter 1.
* A collection of links to VLSI resources including open-source CAD tools and process parameters.
* A student solutions manual that includes answers to odd-numbered problems.
* Certain sections of the book moved online to shorten the page count. These sections are indicated by the “Web Enhanced” icon (shown here in the margin).

Supplements to help instructors with the course include:

* A sample syllabus.
* Lecture slides for an introductory VLSI course.
* An instructor’s manual with solutions.

These materials have been prepared exclusively for professors using the book in a course. Please send email to computing@aw.com for information on how to access them.

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We have become painfully aware of the ease with which mistakes creep into a book. Scores of 3rd edition readers have reported bugs that are now corrected. Despite our best efforts at validation, we are confident that we have introduced a similar number of new errors. Please check the errata sheet at www_cmosvlsi.com/errata.pdf to see if the bug has already been reported. Send your reports to bugs@cmosvlsi.com.

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